

VIN = 5 to 39 V, VOUT = 1.2 to 9 V, 1-channel DC-DC Step down Regulator integrated N-channel Power MOSFET

FEATURES

- 1-channel DC-DC Step Down Regulator Circuit that employs Voltage Mode Switching Control System
- Internal reference voltage is within ±1% accuracy
- Input Voltage Range : PVCC , VCC: 5 V ~ 39 V
- Adjustable Output Voltage Range with external Resistor : 1.2 V ~ 9 V
- Adjustable Switching Frequency with external Resistor : 200 kHz ~ 2 MHz
- Standby mode consumes less than 1 μA current
- Output over voltage protection function
- Output ground short protection function
- Over current protection with adjustable threshold.
- Under voltage lockout function (VREG)
- Thermal Shut Down function
- Adjustable soft-start function
- SSOP024-P-0300F  
( Size : 7.8 mm X 8.1 mm, 0.65 mm pitch ),  
24pin Plastic Shrink Small Outline Package (SSOP Type)

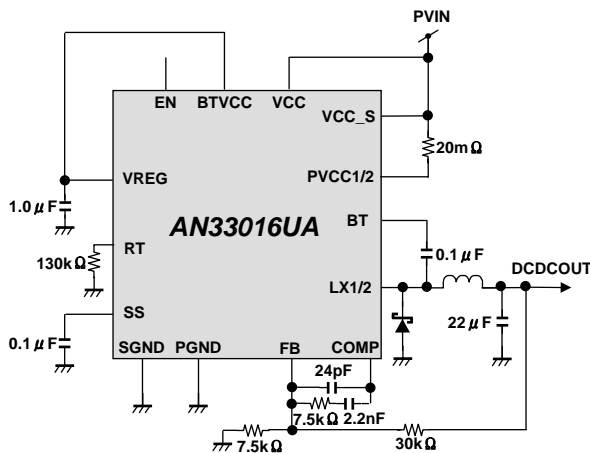
DESCRIPTION

AN33016UA is 1-channel DC-DC Step down Regulator integrated N-channel Power MOSFET and employs the voltage mode switching control system. This IC can be operated with wide input voltage range and is build in several protection functions, so this IC can provide high reliability power supply system. Since it is possible to use up to 2 MHz switching frequency and it is unnecessary to add external parts for High Side Switch, this IC realizes downsizing of set and reducing in the number of external parts. Output voltage is adjustable by user. Maximum current is 1.5 A.

APPLICATIONS

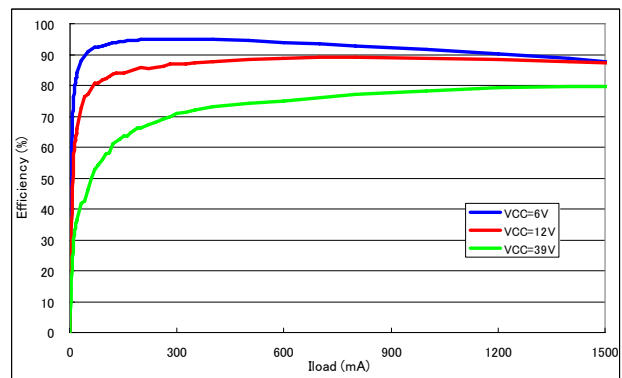
- High Input Voltage Power Systems such as
- Car-Audio system
  - Car-Navigation system
  - OA Equipment
  - Home Appliances etc.

SIMPLIFIED APPLICATION



Notes) This application circuit is an example. The operation of mass production set is not guaranteed. You should perform enough evaluation and verification on the design of mass production set. You are fully responsible for the incorporation of the above application circuit and information in the design of your equipment.

EFFICIENCY CURVE



Condition )  
Vin = 6 , 12 , 25 V, Vout = 5 V,  
Lo = 10 μH, Co = 22 μF, Frequency = 490 kHz

**ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Rating	Unit	Notes
Supply voltage	V <sub>cc</sub>	40	V	*1
Operating free-air temperature	T <sub>opr</sub>	- 40 to + 85	°C	*2
Operating junction temperature	T <sub>j</sub>	- 40 to + 150	°C	*2
Storage temperature	T <sub>stg</sub>	- 55 to + 150	°C	*2
Input Voltage Range	VCC_S,RS	(V <sub>cc</sub> -5.5) to (V <sub>cc</sub> +0.3)	V	*1 *3
Input Voltage Range	BT	-0.3 to (V <sub>cc</sub> +VREG)	V	*1 *4
Input Voltage Range	EN	-0.3 to (V <sub>cc</sub> +0.3)	V	*1 *5
Input Voltage Range	FB,BTVCC,TL_CTRL,SYNC	-0.3 to 5.5	V	*1
Output Voltage Range	FLAG	-0.3 to 5.5	V	*1
	LX1,LX2	- 0.3 to ( V <sub>cc</sub> + 0.3 )	V	*1 *5
ESD	HBM (Human Body Model)	2	kV	—
	MM (Machine Model)	200	V	—

Notes) Do not apply external currents and voltages to any pin not specifically mentioned.

This product may sustain permanent damage if subjected to conditions higher than the above stated absolute maximum rating. This rating is the maximum rating and device operating at this range is not guaranteeable as it is higher than our stated recommended operating range. When subjected under the absolute maximum rating for a long time, the reliability of the product may be affected.

V<sub>cc</sub> is voltage for VCC, PVCC1 and PVCC2. VCC = PVCC1 = PVCC2.

\*1:The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

\*2:Except for the power dissipation, operating ambient temperature, and storage temperature, all ratings are for Ta = 25 °C.

\*3:( V<sub>cc</sub> - 5.5 ) V must not be exceeded - 0.3 V, and ( V<sub>cc</sub> + 0.3 ) V must not be exceeded 60 V

\*4:( V<sub>cc</sub> + VREG ) V must not be exceeded 60 V

\*5:( V<sub>cc</sub> + 0.3 ) V must not be exceeded 60 V

**POWER DISSIPATION RATING**

PACKAGE	θ <sub>JA</sub>	PD ( Ta = 25 °C )	PD ( Ta = 85 °C )	Notes
24 Pin Plastic Shrink Small Outline Package (SSOP Type)	135.1 °C / W	0.925 W	0.481 W	*1

Note). For the actual usage, please refer to the PD-Ta characteristics diagram in the package specification, follow the power supply voltage, load and ambient temperature conditions to ensure that there is enough margin and the thermal design does not exceed the allowable value.

\*1:Glass Epoxy Substrate(4 Layers) [Glass-Epoxy: 50 X 50 X 0.8t(mm)]



**CAUTION**

Although this has limited built-in ESD protection circuit, but permanent damage may occur on it. Therefore, proper ESD precautions are recommended to avoid electrostatic damage to the MOS gates

RECOMMENDED OPERATING CONDITIONS

Parameter	Pin Name	Min.	Typ.	Max.	Unit	Notes
Supply voltage range	VCC	5	12	25	V	*1
	PVCC1					
	PVCC2					
Input Voltage Range	VCC_S	Vcc - 5.5	—	Vcc + 0.3	V	*1
	RS					*2
Input Voltage Range	BT	-0.3	—	Vcc + VREG	V	*1 *3
Input Voltage Range	EN	-0.3	—	Vcc + 0.3	V	*1 *4
Output Voltage Range	LX1,LX2	-0.3	—	Vcc + 0.3	V	*1 *4
Input Voltage Range	FB	-0.3	—	5.5	V	*1
	BTVCC					
	TL_CTRL					
	SYNC					
Output Voltage Range	FLAG	-0.3	—	5.5	V	*1

Note) Do not apply external currents and voltages to any pin not specifically mentioned.

Voltage values, unless otherwise specified, are with respect to GND. GND is voltage for SGND, PGND. SGND = PGND  
Vcc is voltage for VCC, PVCC1 and PVCC2. VCC = PVCC1 = PVCC2.

\*1 : The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

\*2:( Vcc - 5.5 ) V must not be exceeded - 0.3 V, and ( Vcc + 0.3 ) V must not be exceeded 60 V

\*3:( Vcc + VREG ) V must not be exceeded 60 V

\*4:( Vcc + 0.3 ) V must not be exceeded 60 V

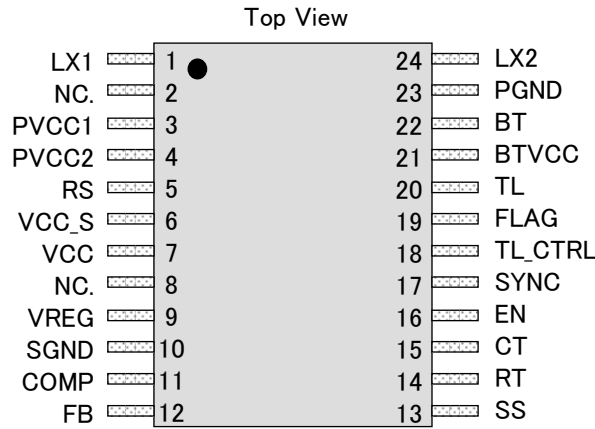
**ELECTRICAL CHARACTERISTICS**

Co = 22 μF, Lo = 10 μH, VOUT Setting = 5.0 V, VCC = 12 V, RT = 130 kΩ,  
 Ta = 25 °C ± 2 °C unless otherwise noted.

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
<b>Current Consumption</b>							
Quiescent current	I <sub>CQ</sub>	No switching FB = 1.1 V EN = High (3.3 V)	—	1.0	1.4	mA	—
Standby current	I <sub>STBY</sub>	EN = Low	—	0.01	1	μA	—
<b>BGR</b>							
Feedback voltage	V <sub>REF</sub>	FB connected to COMP with gain of 1.5 times	0.99	1.0	1.01	V	—
<b>Enable (EN)</b>							
Low input threshold	V <sub>IL1</sub>	—	—	—	0.4	V	—
High input threshold	V <sub>IH1</sub>	—	2.0	—	—	V	—
EN terminal input current	V <sub>IC1</sub>	EN = 3.3 V	—	33	70	μA	—
<b>SYNCHRONIZATION (SYNC)</b>							
Low input threshold	V <sub>IL2</sub>	—	—	—	0.4	V	—
High input threshold	V <sub>IH2</sub>	—	2.0	—	—	V	—
<b>Oscillator</b>							
Oscillator frequency	F <sub>OUT1</sub>	RT = 130 kΩ	465	490	515	kHz	—
Oscillator frequency range	F <sub>OUT2</sub>		200	—	2000	kHz	—
External sync frequency range	F <sub>SYNC</sub>	RT = 130 kΩ Fout1 = 490 kHz	520	—	730	kHz	—
<b>Over-current protection</b>							
Over-current threshold voltage	V <sub>OCP</sub>	(VCC_S-VRS)	66	75	84	mV	*1
<b>Over-voltage protection</b>							
Over-voltage threshold voltage for VFB	V <sub>OVP1</sub>	For FB	1.14	1.22	1.30	V	—
Over-voltage threshold voltage for VCC	V <sub>OVP2</sub>	For VCC	40	45	50	V	—
<b>Internal regulator</b>							
Internal regulator output voltage	V <sub>REG</sub>	C <sub>REG</sub> = 1 μF	4.5	5.0	5.3	V	—
<b>GND short protection</b>							
Short detection voltage	V <sub>SCP</sub>	monitor FB	0.15	0.3	0.45	V	—

Note) \*1 : This parameter is tested with DC measurement.

PIN CONFIGURATION

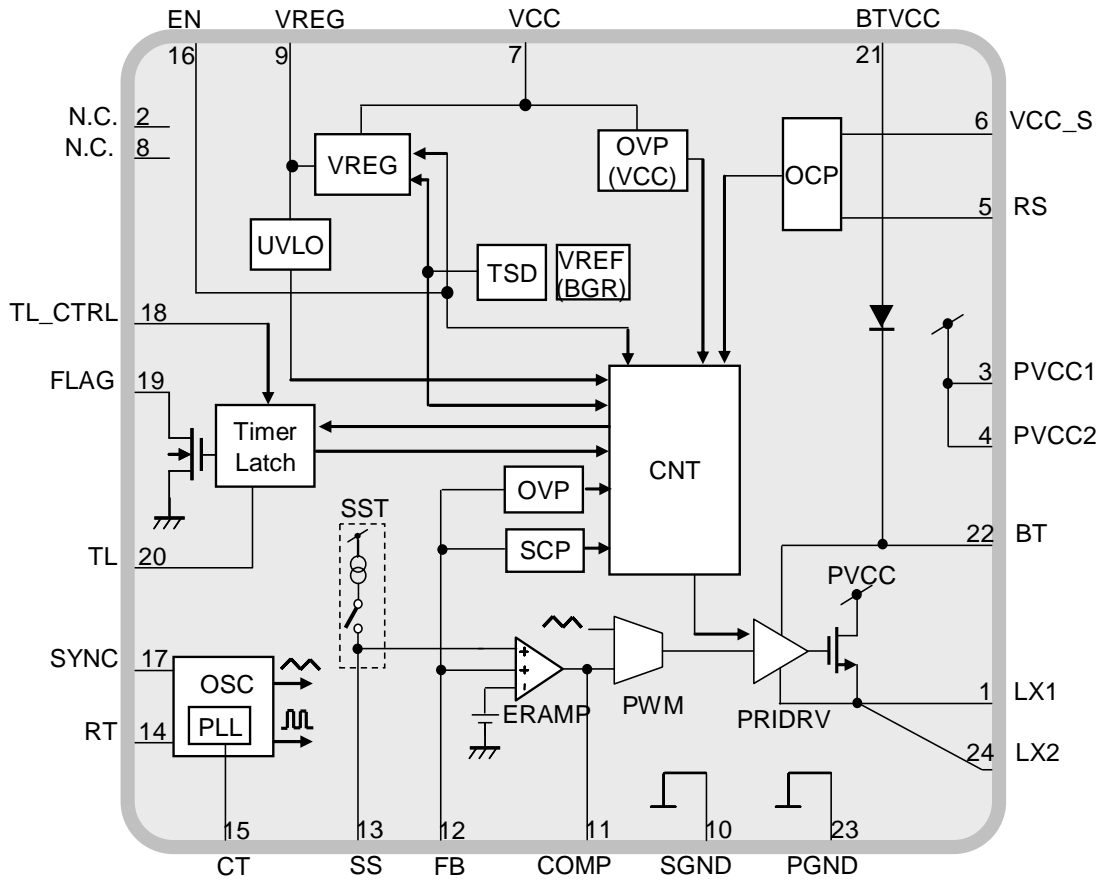


PIN FUNCTIONS

Pin No.	Pin name	Type	Description
1	LX1	Output	Connect to an external inductor and schottky diode
2	NC	—	No connection
3	PVCC1	Power Supply	Power supply pin for internal driver
4	PVCC2	Power Supply	Power supply pin for internal driver
5	RS	Input	Connection to current sensing port for OCP
6	VCC_S	Input	VCC pin connection to current sensing port for OCP
7	VCC	Power Supply	Power supply pin
8	NC	—	No connection
9	VREG	Output	Connect to an external capacitor for internal regulator
10	SGND	Ground	Ground pin
11	COMP	Output	Error amplifier output
12	FB	Input	Error amplifier negative input
13	SS	Output	Soft-start capacitor connection pin
14	RT	Output	Connect to an external resistor for adjustment of oscillation frequency
15	CT	Output	Low Pass filter function pin for PLL
16	EN	Input	Enable pin
17	SYNC	Input	External clock input for adjustment of oscillation frequency
18	TL_CTRL	Input	Connect to high to disable shut-down function by OCP/SCP
19	FLAG	Output	Error flag output pin
20	TL	Output	Connect to an external capacitor for adjustment of over-current detection time
21	BTVCC	Input	Boot strap input pin
22	BT	Input	Connect to an external capacitor for Boot strap
23	PGND	Ground	Power ground pin
24	LX2	Output	Connect to an external inductor and schottky diode

Notes) Concerning detail about pin description, please refer to OPERATION and APPLICATION INFORMATION section.

FUNCTIONAL BLOCK DIAGRAM



Notes) This block diagram is for explaining functions. Part of the block diagram may be omitted, or it may be simplified.

## OPERATION

### 1. Power ON/OFF sequence

Note) The characteristics listed below are reference values derived from the design of the IC and are not guaranteed.

AN33016UA consists of one channel and it can be turned ON and OFF by using the EN pin.

EN > 2.0 V : Enabled  
EN < 0.4 V : Disabled

#### 1. Power ON Sequence :

- VCC rises to a desired voltage level.  
(A 10 ms rise time or more is recommended to control and limit any abnormal current flow via the power transistor when VCC is rising.)
- Apply a voltage level of 2.0 V or higher at EN pin after VCC is steady and the DCDC will begin to operate.  
(It is possible to connect the EN pin to VCC through a resistor, and, in that case, when VCC rises, DCDC will begin to operate.)
- When VREG voltage reaches 4.9 V and above, and after a delay time (charging time of the soft start capacitor) decided by an external capacitor, the DCDC will start to operate.

#### 2. Power OFF Sequence :

- To turn OFF the DCDC output, apply a voltage of 0.4 V or lower to EN pin.
- VOUT will drop after EN pin becomes Low.  
(The discharge time is dependent on the applied load current and the feedback resistance connected at the output.)
- The DCDC will turn OFF if the VCC level becomes low even before EN pin becomes low.  
The above scenario occurs when the VREG voltage decreases to 4.0 V or less.  
(However, the DCDC output voltage will also decrease with VCC when the VCC level drops below a certain minimum level required to maintain the output voltage level.)

#### 3. Points to take note of when re-starting the DCDC :

- Please allow a waiting time of 10 ms or more for the discharge time of the soft start capacitor when starting up the DCDC again after turning it OFF.  
The output voltage might overshoot without the soft start function working properly if the DCDC is re-started immediately after it is turned OFF.

#### 4. Points to take note of when shut down:

- Please apply a voltage of Low level or lower to EN PIN when turn OFF the DCDC.

OPERATION (Continued)

2. Start / Stop Control Timing Chart

Note) The characteristics listed below are reference values derived from the design of the IC and are not guaranteed.

- ON/OFF operation sequence by EN pin control.

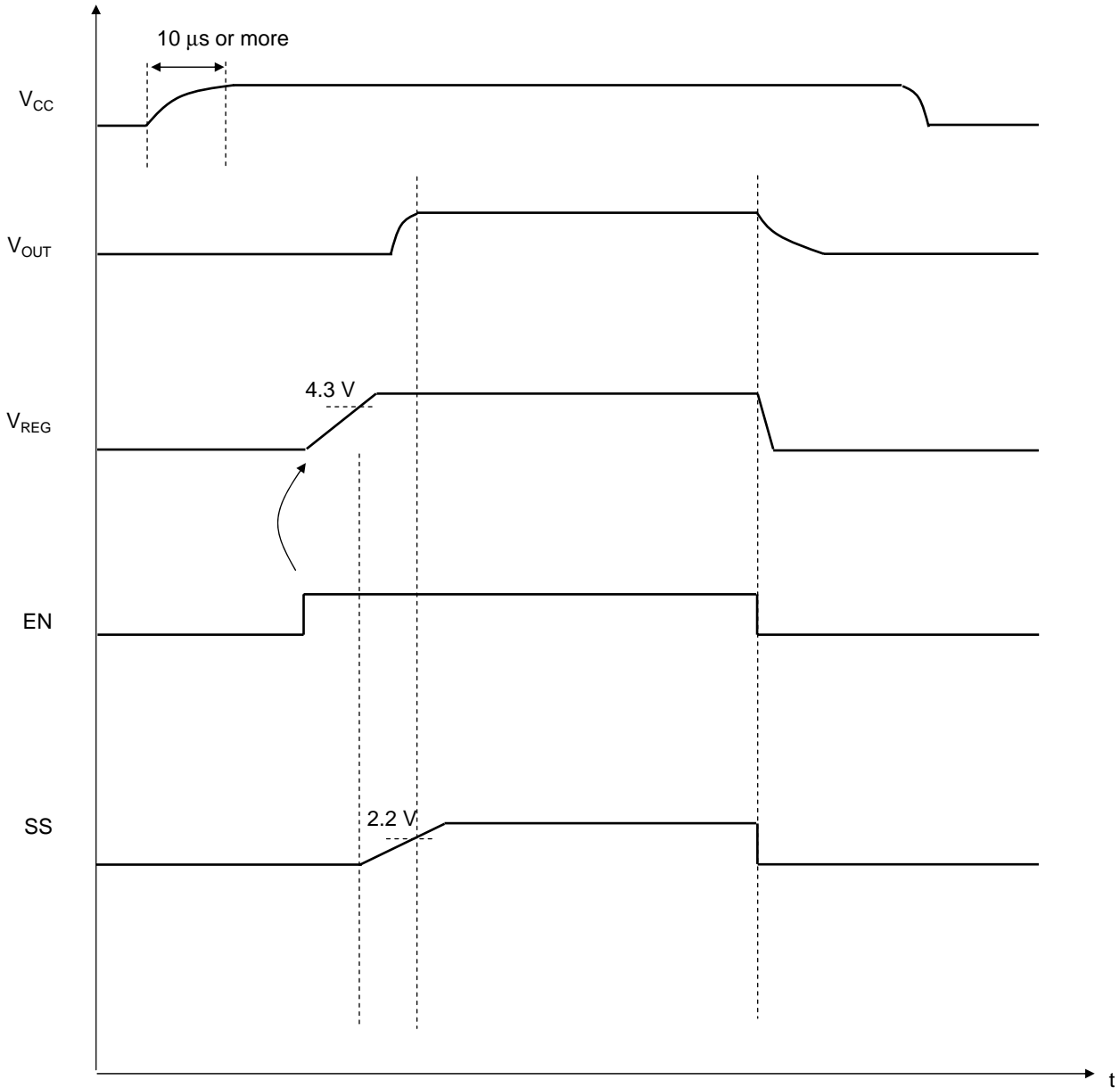


Figure : Power ON/OFF sequence by EN

Note) All values given in the above figure are typical values.



**OPERATION (Continued)**

**2. Start / Stop Control Timing Chart**

Note) The characteristics listed below are reference values derived from the design of the IC and are not guaranteed.

- ON/OFF operation sequence by VCC pin control (EN pin is connected to VCC).

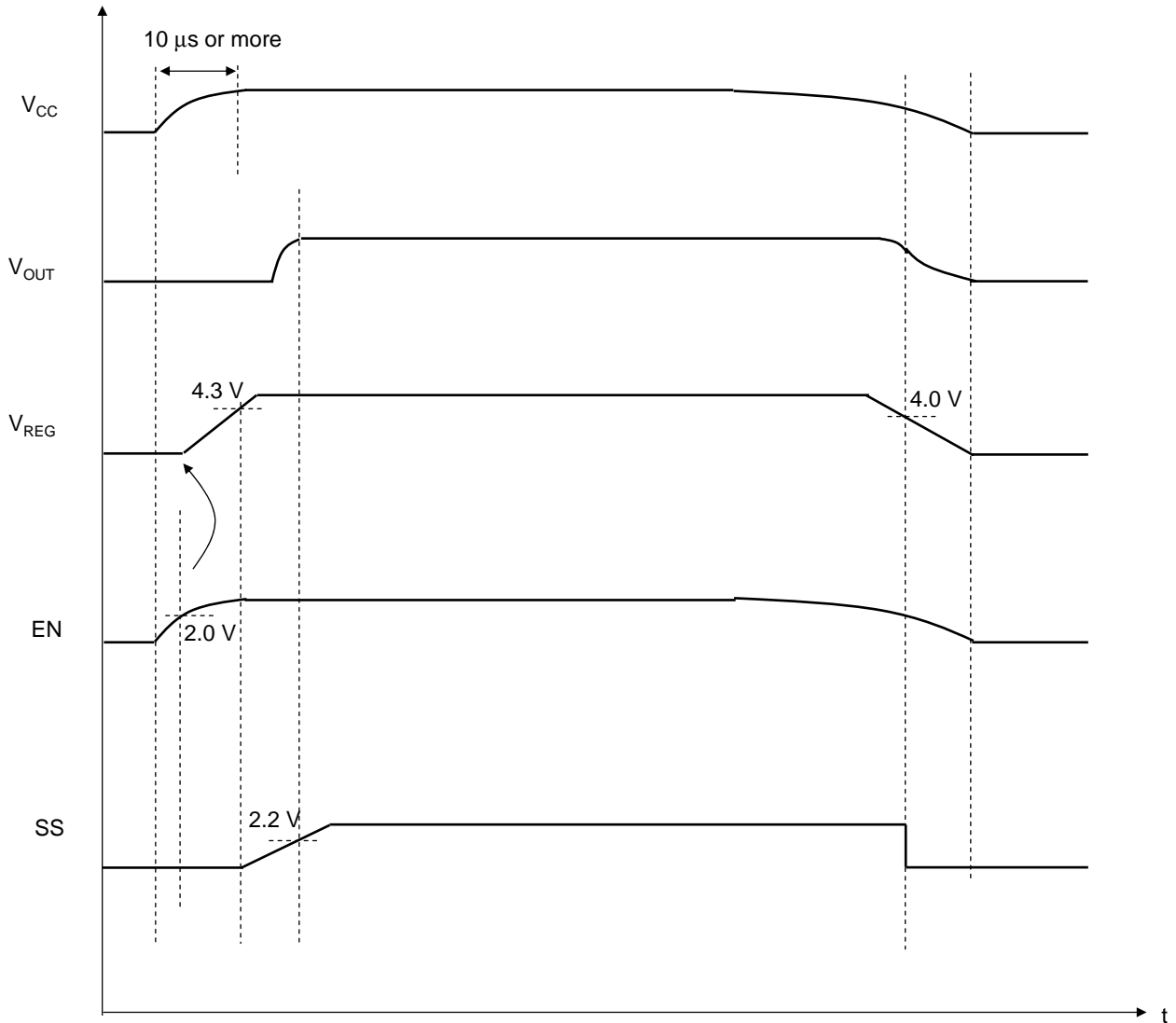


Figure : Power ON/OFF sequence by VCC/EN

Note) All values given in the above figure are typical values.

## OPERATION (Continued)

### 3. Output voltage setting

Note) The characteristics listed below are reference values derived from the design of the IC and are not guaranteed.

The output voltage of AN33016UA is set with the external feedback resistance divider arranged between the terminal FB and GND between the DCDC output and the terminal FB. The output voltage is decided depending on the following equation.

$$V_{out} = 1.0 \times \left[ 1 + \frac{R_a}{R_b} \right]$$

### 4. Min/Max Duty Operation

Note) The characteristics listed below are reference values derived from the design of the IC and are not guaranteed.

MinDuty is decided by the minimum ON time. The minimum ON time,  $T_{on}(\text{min})$ , is the time that this IC can turn on the high side switch. This is decided by the gate capacitance of the high side switch and the internal timing delay. The following attention is necessary because in applications where the Input/Output voltage difference is great, and the switching frequency is high, there is a possibility to reach the limiting value of the minimum ON time. The minimum ON time,  $T_{on}(\text{min})$ , is about 200ns (max).

This IC has the function of MaxDuty, which will not exceed a certain definite value for safety reasons in case of abnormal circumstances. The following attention is necessary because in applications where the Input/Output voltage difference is close, and the switching frequency is high, there is a possibility to reach the limiting value of the minimum OFF time. The minimum OFF time,  $T_{off}(\text{min})$ , is about 200ns (max).

$$T_{on}(\text{min}) < \frac{V_{out}}{V_{in}} \times \frac{1}{F}$$

$$T_{off}(\text{min}) < \left( 1 - \frac{V_{out}}{V_{in}} \right) \times \frac{1}{F}$$

\*) F : Switching frequency

When operating near the Min/Max limited duty, the ripple voltage and the inductor current ripple increases even if the output voltage is stabilized. It is recommended to use on the condition when the turn on switching time and turn off switching time are 200ns or more.

\*) Please take note of the output voltage setting when the switching frequency is high.

**OPERATION (Continued)**

**5. Oscillation Frequency**

Note) The characteristics listed below are reference values derived from the design of the IC and are not guaranteed.

The switching frequency of the built-in oscillator circuit can be set from 200 kHz to 2000 kHz, determined by the resistance of the terminal RT, set by external resistance. The setting accuracy of the frequency is approximately ±5%. The equation and the corresponding table are described as follows.

RT [KΩ]	OSC Frequency (KHz)	RT [KΩ]	OSC Frequency (KHz)
22	2067	91	675
24	1950	100	622
27	1789	110	572
30	1661	120	525
33	1550	130	490
36	1448	150	430
39	1365	160	404
43	1265	180	361
47	1176	200	329
51	1099	220	301
56	1024	240	272
62	943	270	248
68	873	300	225
75	799	330	205
82	737	360	187

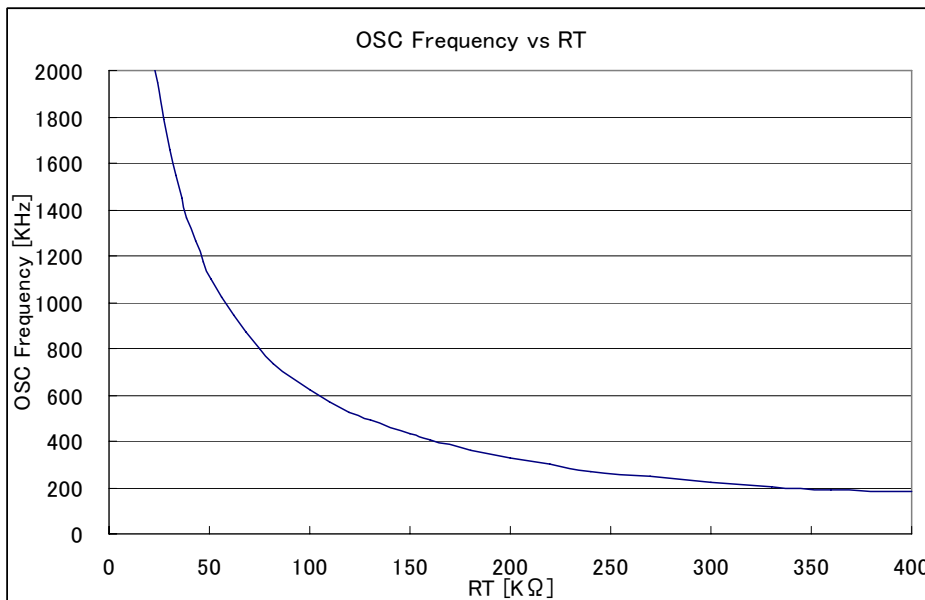


Figure : switching frequency vs external resistance

OPERATION (Continued)

6. Over-Current Protection

Note) The characteristics listed below are reference values derived from the design of the IC and are not guaranteed.

Over-current protection function (OCP) turns off the Power MOS in IC when the voltage difference of the external resistance  $R_{sense}$  exceeds 75mV(Typ.) to stop the supply of current from VCC to VOUT. Detection current  $I_{sense}$  can be calculated as:

$$I_{sense} = 75 \text{ mV} / R_{sense}$$

The over-current protection function operates via pulse-by-pulse control, and Duty is limited during the over-current protection period. Moreover, because the over-current detects the peak current that flows through  $R_{sense}$ , it is necessary to convert it from desired output current  $I_{out}$  value (Refer to Figure ). Equation is shown below.

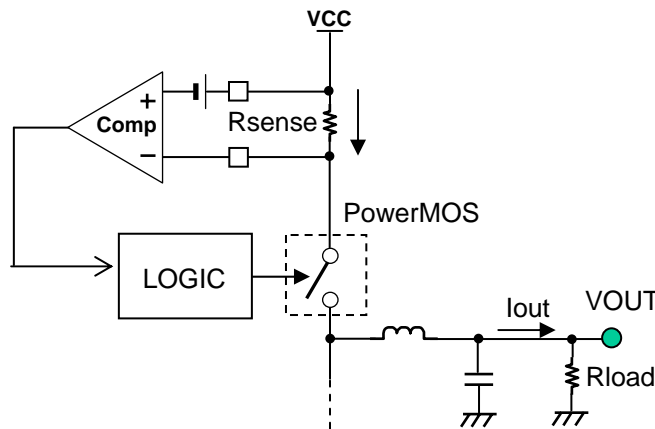


Figure : Over-Current Protection circuit block diagram

$$R_{sense} \approx \frac{0.075}{I_{out} + \frac{V_{OUT} \cdot (V_{CC} - V_{OUT})}{2 \cdot F \cdot L \cdot V_{CC}}}$$

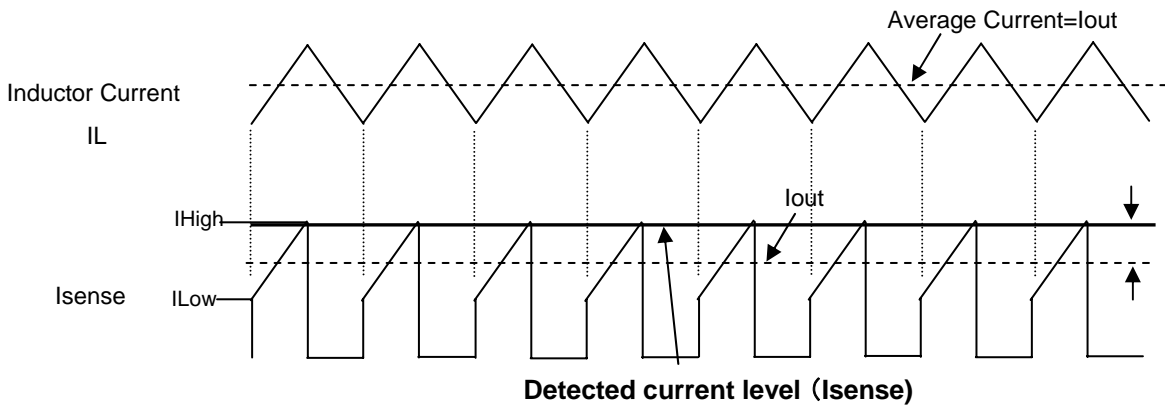


Figure : Method of detection of Over-Current Protection function

APPLICATIONS INFORMATION

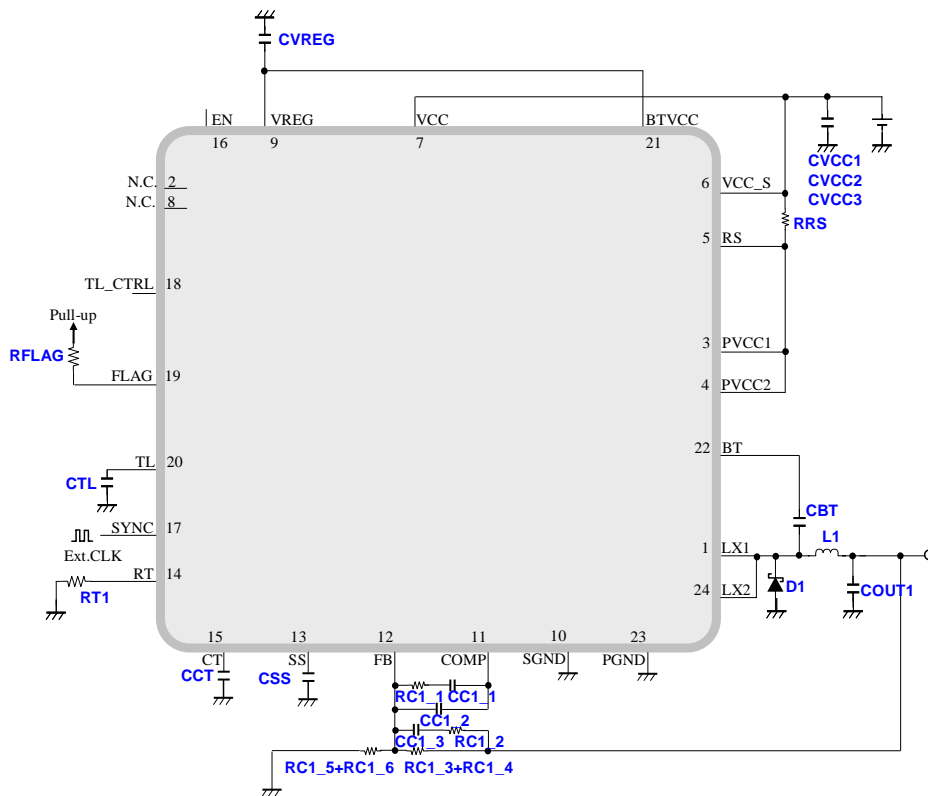


Figure : Application circuit

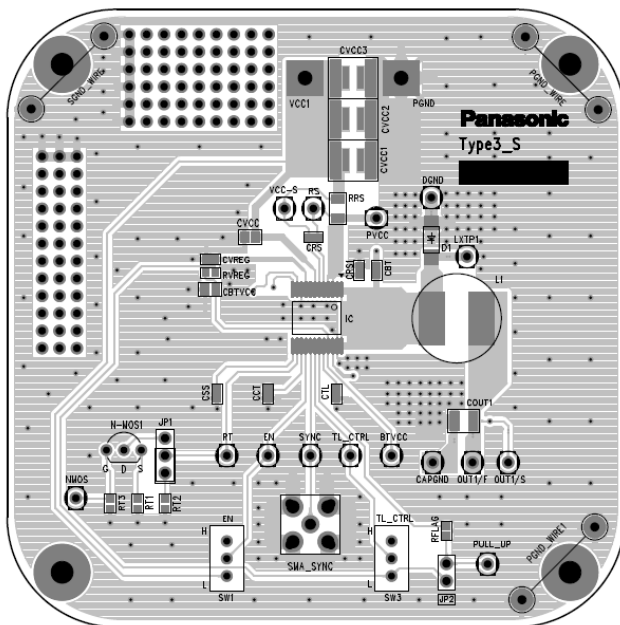


Figure : Top Layer with silk screen ( Top View ) with Evaluation board

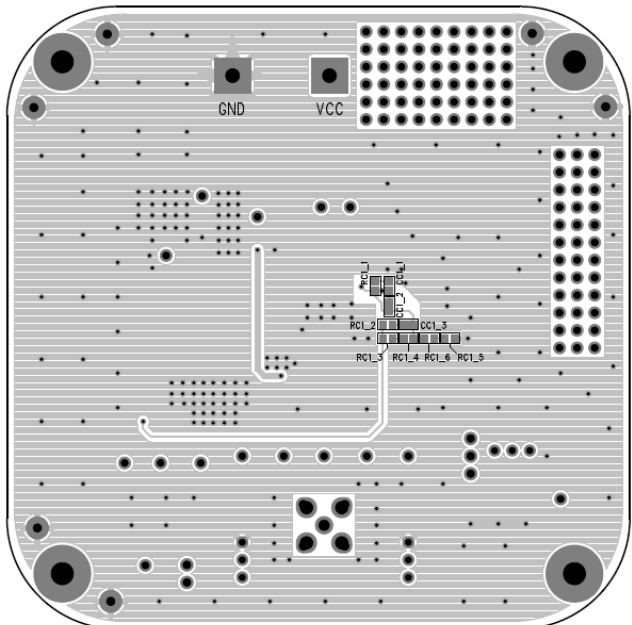


Figure : Bottom Layer with silk screen ( Bottom View ) with Evaluation board

Notes) This application circuit and layout is an example. The operation of mass production set is not guaranteed. You should perform enough evaluation and verification on the design of mass production set. You are fully responsible for the incorporation of the above application circuit and information in the design of your equipment.

**APPLICATIONS INFORMATION ( Continued )**

Reference	Part Name	Value	Maker	Description
CBT,CCT,CSS,CTL	GCM188R11C104KA01J	0.1 $\mu$ F	Murata	Setting Capacitor
CC1_1	GCM1882C1H222JA01J	2.2nF	Murata	Compensation Capacitor
CC1_2	GCM1882C1H240JA01J	24pF	Murata	Compensation Capacitor
CC1_3	GCM1882C1H471JA01J	470pF	Murata	Compensation Capacitor
CVREG	GCM188R71C105KA49J	1 $\mu$ F	Murata	VREG Capacitor
CVCC1,CVCC2, CVCC3	CKG57NX7R1H226MT	22 $\mu$ F	TDK	Input Capacitor
COUT1	TMK325C7226MM-T	22 $\mu$ F	TAIYO,YUDEN	Output Capacitor
L1	CDRH8D43-100NC	10 $\mu$ H	SUMIDA	Inductor
IC1	AN33013UA	-	Panasonic	1ch DCDC Converter
D1	DB24416	-	Panasonic	Schottky Diode
RC1_1	ERA3AEB752V	R=7.5K	Panasonic	Compensation & Feedback Resistor
RC1_2	ERA3AEB152V	R=1.5K	Panasonic	Compensation & Feedback Resistor
RC1_3	ERJ3GEY0R00V	R=0	Panasonic	Compensation & Feedback Resistor
RC1_4	ERA3AEB303V	R=30K	Panasonic	Compensation & Feedback Resistor
RC1_5	ERJ3GEY0R00V	R=0	Panasonic	Compensation & Feedback Resistor
RC1_6	ERA3AEB752V	R=7.5K	Panasonic	Compensation & Feedback Resistor
RVREG	ERJ3GEY0R00V	R=0	Panasonic	-
RFLAG	ERA3AEB204V	R=200K	Panasonic	Pull-up Resistor
RT1,RT2,RT3	ERA3AEB134V	R=130K	Panasonic	OSC Setting Resistor
RRS	ERJ8BWFR030V	R=30m	Panasonic	OCP Sense Resistor

Figure : Recommended component



PACKAGE INFORMATION ( Reference Data )

Power dissipation (Supplementary explanation)

[Experiment environment]

Power Dissipation (Technical Report) is a result in the experiment environment of SEMI standard conformity. (Ambient air temperature (Ta) is 25 degrees C)

[Supplementary information of PWB to be used for measurement]

The supplement of PWB information for Power Dissipation data (Technical Report) are shown below.

Indication	Total Layer	Resin Material
Glass-Epoxy	1-layer	FR-4
4-layer	4-layer	FR-4

[Notes about Power Dissipation (Thermal Resistance) ]

Power Dissipation values (Thermal Resistance) depend on the conditions of the surroundings, such as specification of PWB and a mounting condition , and a ambient temperature. (Power Dissipation (Thermal Resistance) is not a fixed value.)

The Power Dissipation value (Technical Report) is the experiment result in specific conditions (evaluation environment of SEMI standard conformity) ,and keep in mind that Power Dissipation values (Thermal resistance) depend on circumference conditions and also change.

[Definition of each temperature and thermal resistance]

Ta : Ambient air temperature

※The temperature of the air is defined at the position where the convection, radiation, etc. don't affect the temperature value, and it's separated from the heating elements.

Tc : It's the temperature near the center of a package surface. The package surface is defined at the opposite side if the PWB.

Tj : Semiconductor element surface temperature (Junction temperature.)

Rth(j-c) : The thermal resistance (difference of temperature of per 1 Watts) between a semiconductor element junction part and the package surface

Rth(c-a) : The thermal resistance (difference of temperature of per 1 Watts) between the package surface and the ambient air

Rth(j-a) : The thermal resistance (difference of temperature of per 1 Watts) between a semiconductor element junction part and the ambient air

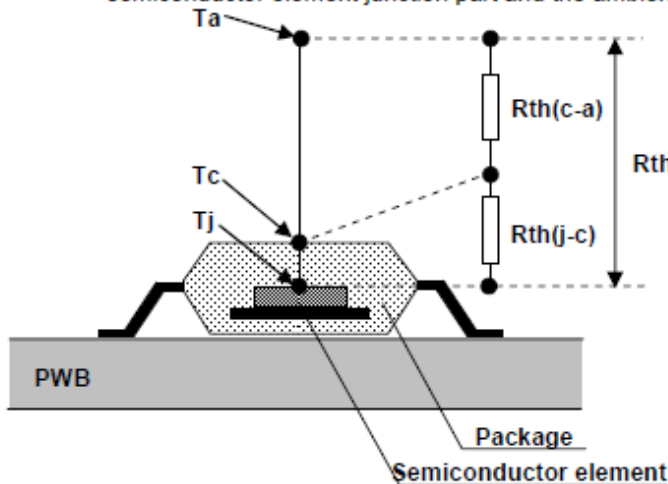


Fig1. Definition image

[Definition formula]

$$Tj = \{Rth(j-c) + Rth(c-a)\} \times P + Ta$$

$$= Rth(j-a) \times P + Ta$$

$$Rth(j-c) = \frac{Tj - Tc}{P} \quad (^\circ\text{C/W})$$

$$Rth(c-a) = \frac{Tc - Ta}{P} \quad (^\circ\text{C/W})$$

$$Rth(j-a) = \frac{Tj - Ta}{P} \quad (^\circ\text{C/W})$$

$$= Rth(j-c) + Rth(c-a)$$

P: power(W)



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3. When the application system is designed by using this LSI, be sure to confirm notes in this book.  
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**USAGE NOTES**

1. When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not to exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.

Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.

2. Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.
3. Pay attention to the direction of LSI. When mounting it in the wrong direction onto the PCB (printed-circuit-board), it might smoke or ignite.
4. Pay attention in the PCB (printed-circuit-board) pattern layout in order to prevent damage due to short circuit between pins. In addition, refer to the Pin Description for the pin configuration.
5. Perform a visual inspection on the PCB before applying power, otherwise damage might happen due to problems such as a solder-bridge between the pins of the semiconductor device. Also, perform a full technical verification on the assembly quality, because the same damage possibly can happen due to conductive substances, such as solder ball, that adhere to the LSI during transportation.
6. Take notice in the use of this product that it might break or occasionally smoke when an abnormal state occurs such as output pin-VCC short (Power supply fault), output pin-GND short (Ground fault), or output-to-output-pin short (load short) .

And, safety measures such as an installation of fuses are recommended because the extent of the above-mentioned damage and smoke emission will depend on the current capability of the power supply.

7. The protection circuit is for maintaining safety against abnormal operation. Therefore, the protection circuit should not work during normal operation.  
  
Especially for the thermal protection circuit, if the area of safe operation or the absolute maximum rating is momentarily exceeded due to output pin to VCC short (Power supply fault), or output pin to GND short (Ground fault), the LSI might be damaged before the thermal protection circuit could operate.
8. Unless specified in the product specifications, make sure that negative voltage or excessive voltage are not applied to the pins because the device might be damaged, which could happen due to negative voltage or excessive voltage generated during the ON and OFF timing when the inductive load of a motor coil or actuator coils of optical pick-up is being driven.
9. The product which has specified ASO (Area of Safe Operation) should be operated in ASO
10. Verify the risks which might be caused by the malfunctions of external components.
11. Connect the metallic plates on the back side of the LSI with their respective potentials (AGND, PVIN, LX). The thermal resistance and the electrical characteristics are guaranteed only when the metallic plates are connected with their respective potentials.

## Request for your special attention and precautions in using the technical information and semiconductors described in this book

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- (5) When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not to exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.  
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